



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of “Quality Parts,Customers Priority,Honest Operation,and Considerate Service”,our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

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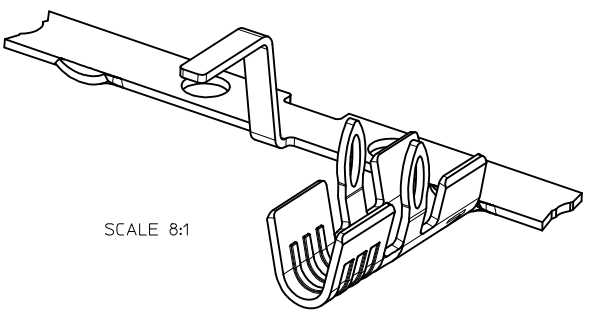
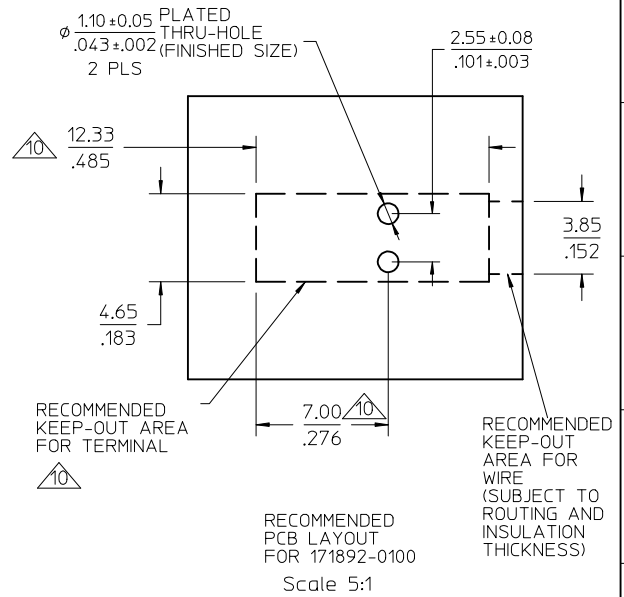
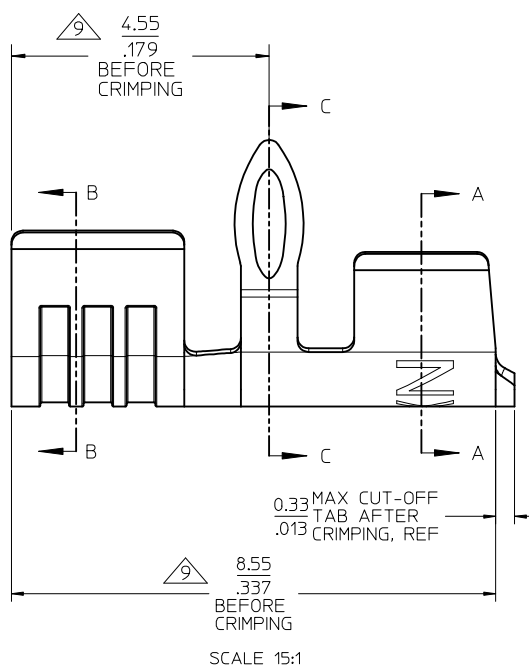


MATERIAL NUMBER	MATERIAL	PLATING	COND SIZE	MAX INS DIA	MAX PCB THICKNESS
171892-0100	BRASS	RMT	16~18 AWG	2.31 / .091 (UL1007)	1.57 / .062

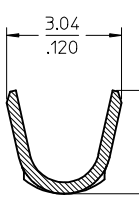
LEGEND: 171892-WXYZ

W = PLATING  
 (0 = REFLOWED MATTE TIN)  
 X = CRIMP SIZE  
 (1 = 16~18AWG, THIN (UL1007) INSUL / .062 PCB)  
 YZ = NOT USED  
 (00)

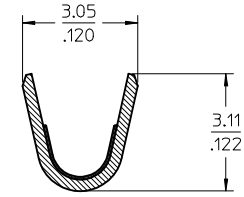
- NOTES:
- MATERIAL: BRASS
  - FINISH:  
RMT = OVERALL REFLOWED MATTE TIN, 0.00152 / .000060 MIN OVER 0.00127 / .000050 MIN NICKEL, OVERALL
  - PRODUCT SPECIFICATION: PS-171892-001
  - PACKAGING INFORMATION: PK-171892-001  
3,000 PER 24" CARDBOARD REEL
  - MATES WITH: N/A (FOR SOLDERING TO PCB)
  - THIS PART CONFORMS TO CLASS B REQUIREMENTS OF COSMETIC SPEC PS-45499-002.
  - TERMINAL DESIGNED FOR THRU-HOLE SOLDERING, NOT FOR PRESS-FIT. INTERFERENCE FIT PROVIDES RETENTION OF TERMINAL TO BOARD DURING SOLDERING ONLY.
  - MAX INSULATION DIAMETER AND MAX PCB THICKNESS SHOWN ARE GUIDELINES TO PRODUCE 0.50 / .020 OR MORE SOLDER-TAIL PROTRUSION.
  - CRIMPING PROCESS CAUSES TERMINAL GROWTH OF APPROXIMATELY 1.0 / .04.
  - INCLUDING TERMINAL GROWTH AND WIRE BRUSH LENGTH.



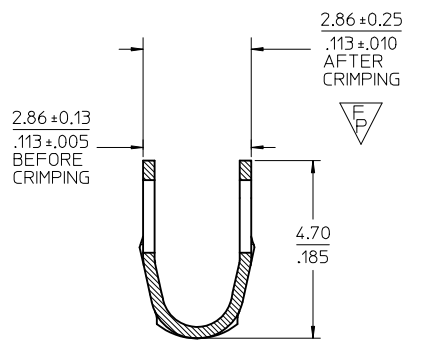
SCALE 8:1



SECTION A-A  
INSULATION CRIMP



SECTION B-B  
CONDUCTOR CRIMP



SECTION C-C  
SOLDER-TAILS

ADD PS & PK EC NO: UCP2013-5022 DRWN: BANDERSON 2013/05/22 CHKD: SSOUSEK 2013/05/22 APPR: FSMITH 2013/06/11 REV: A1	QUALITY SYMBOLS	GENERAL TOLERANCES (UNLESS SPECIFIED)	DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
	▽=0	mm INCH	MM/IN	10:1	METRIC	☉
	▽=0	4 PLACES ± --- ± ---	DRAWN BY DATE	<b>SOLDERRIGHT          RIGHT-ANGLE BOARD-IN          TERMINAL</b>  <b>molex</b>  DOCUMENT NO. SD-171892-001 SHEET NO. 1 OF 1		
	▽=1	3 PLACES ± --- ± .010	CHECKED BY DATE			
		2 PLACES ± 0.25 ± .014	SSOUSEK 2013/05/01			
	1 PLACE ± 0.35 ± ---	APPROVED BY DATE				
	0 PLACE ± --- ± ---	FSMITH 2013/05/13				
	ANGULAR ±1/2°	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE CHART			